

Product/ Process Change Notification						
1. PCN No.:	QPCN11033					
2. Subject:	SOT-2x Package Copper Bond Wire					
3. To:	Customers					
4. Issued by:	PMD PM					
5. Issue date:	November. 1, 2011					
6. Proposed first ship date for change:	January. 31, 2012					
7. Affected Product Identification						
MOSFET Product Family > SOT-2x Package						
8. Change Description : (OLD Vs. NEW Com	nparison)					
Old:	New:					
> Gold bond-wire	> Copper bond-wire					
9. Reason for Change:						
Enhancement to long-term product reliability. (Copper offers lower Electrical Resistivity, high	Enhancement to long-term product reliability. (Copper offers lower Electrical Resistivity, high current capability than Gold wire)					
10. Anticipated Impact: (form, fit, function, qua	lity or reliability)					
1. Data sheet: 2. Reliability/performance: 3. Packing code (order code): 4. Inner construction: No Change No Change No Change						
11. Qualification plan/result:						
Refer to the appendix A and B						
12. Sample availability Date:	Please contact your regional Taiwan Semiconductor Sales office for sample availvalbility.					
13. Tentative implementation date:	February. 2012					
14. Remarks						
There will be no change to part numbering. Products converted to copper wire will have date code 2B1 or later.						
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)	This PCN is considered approved, without further notification, unless we receive specific customer concerns before JAN end, 2012 as specified by contract.					
16. Approved by:						



Product/ Process Change Notification Customer Approval Form

(Please tick the field what is valid for you!)

		(1 lease tick	the held what is valid for	you: /
	We agree with	this proposed chang	e and its schedule.	
	We have object	tions		
	We need more	information:		
	We need samp	le:		
Con	npany:			
Nan	ne:			
Add	lress:			
Sign	nature:		Date:	
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Product/ Process Change Notification

Appendix A

QPCN11033 PARTS LIST

SOT-23	SOT-26	
TSM2312CX	TSM6988DCX6	
TSM2310CX	TSM9966DCX6	
TSM2314CX	TSM3460CX6	
TSM2302CX	TSM3462CX6	
TSM3400CX	TSM3446CX6	
TSM3404CX	TSM3900DCX6	
TSM2306CX	TSM3442CX6	
TSM2318CX	TSM3424CX6	
TSM2N7002KCX	TSM3454CX6	
TSM2308CX	TSM3433CX6	
TSM2328CX	TSM3443CX6	
TSM2323CX	TSM3441CX6	
TSM2311CX	TSM3493CX6	
TSM2313CX	TSM3911DCX6	
TSM2301BCX	TSM3481CX6	
TSM2301CX	TSM3455CX6	
TSM2307CX	TSM3457CX6	
TSM3401CX	SOT-25	
TSM2303CX	TSM3461CX5	



Product/ Process Change Notification

Appendix B

Package: SOT-2x

Qualification Result Summary:

NO.	ITEMS	TEST CONDITION	S.S	RESULT (S.S / REJECT)
1	TOT	Cold : -65°C (+0 / -10)°C		
	TCT (Temperature Cycle Test)	Hot: 150°C (+15/-0)°C	77	77 / 0
		500 cycles		
2	HTSL	Temperature: 150°C	77	77 / 0
	(High Temperature Storage Life)	Duration:1000hrs		
3	Wire Pull test	>6g	60 wires	60 / 0
4	Ball Share test	>45g	25 wires	25 / 0